

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Joon-seo Son</td> <td>12/27/2007</td> </tr> <tr> <td>O-Seob Jeon</td> <td>12/27/2007</td> </tr> <tr> <td>Taek-keun Lee</td> <td>12/27/2007</td> </tr> <tr> <td>Byoung-ok Lee</td> <td>12/27/2007</td> </tr> </tbody> </table>		Name	Execution Date	Joon-seo Son	12/27/2007	O-Seob Jeon	12/27/2007	Taek-keun Lee	12/27/2007	Byoung-ok Lee	12/27/2007
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RECEIVING PARTY DATA											
Name:	Fairchild Korea Semiconductor, Ltd.										
Street Address:	82-3, Dodang-dong, Womni-gu										
Internal Address:	Gyeonggi-do										
City:	Bucheon Si										
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF										
PROPERTY NUMBERS Total: 1											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11970911</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11970911						
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Application Number:	11970911										
CORRESPONDENCE DATA											
Fax Number:	(585)325-5458										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	3023023 (FS-29842-US)										
NAME OF SUBMITTER:	Thomas R. FitzGerald										
Total Attachments: 2											

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**PATENT
 REEL: 020334 FRAME: 0253**

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FAIRCHILD SEMICONDUCTOR CORPORATION**Assignment**

As a below named inventor or joint inventor of an invention or improvement entitled:

**POWER DEVICE PACKAGE COMPRISING METAL TAB DIE ATTACH PADDLE
(DAP) AND METHOD OF FABRICATING THE PACKAGE
(Attorney Docket No. 3023023 (FS-29482-US))**

for which I have executed an application for Letters Patent of the United States of America, on an even date herewith; and

WHEREAS, FAIRCHILD KOREA SEMICONDUCTOR, LTD., a Large Entity, organized and existing under the laws of the Republic of Korea, having a principal place of business at (420-711) 82-3 Dodang-Dong, Wonmi-gu, Bucheon-si, Gyeonggi-do, Korea, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have sold, assigned, transferred, and set over, and by these presents do hereby sell, assign, transfer and set over, unto said FAIRCHILD KOREA SEMICONDUCTOR, LTD., its successors, legal representatives, and assigns, my entire right, title and interest in, to, and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuation applications thereof, and all Letters Patent of the United States of America which may be granted thereof and all reissues and extensions hereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention, all rights to register said invention in appropriate registries, and all Letters Patent which may be granted for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to said FAIRCHILD KOREA SEMICONDUCTOR, LTD., its successors, legal representatives, and assigns, in accordance with the terms of this instrument.

And I hereby covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

And I hereby further covenant and agree that I will communicate to said FAIRCHILD KOREA SEMICONDUCTOR, LTD., its successors, legal representatives, and assigns, any fact known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisions, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid said FAIRCHILD KOREA SEMICONDUCTOR, LTD., its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Attorney Docket:
3023023 (FS-29482-US)

IN TESTIMONY WHEREOF, I authorize and affirm said assignments with the signature(s) set forth below on the indicated date(s).

Inventors:

<u>Joon-seo Son</u> Joon-seo Son	<u>Dec 27, 2007</u> Date
<u>O-seob Jeon</u> O-seob Jeon	<u>Dec 27, 2007</u> Date
<u>Tack-Keun Lee</u> Tack-keun Lee	<u>Dec 27, 2007</u> Date
<u>Byoung-ok Lee</u> Byoung-ok Lee	<u>Dec 27, 2007</u> Date